

Appl. No. : 10/036,957  
Filed : December 20, 2001

### AMENDMENTS TO THE SPECIFICATION

**Please amend the specification as follows:**

**Please delete the paragraph at page 2 extending from line 10 through line 13, and insert therefor the following replacement paragraph:**

Application Serial No. [[--/---,---,]]60/338,004, entitled MICRO-SPRING CONFIGURATIONS FOR POWER DELIVERY FROM VOLTAGE REGULATOR MODULES TO INTEGRATED CIRCUITS AND MICROPROCESSORS, by Joseph T. DiBene II, David H. Hartke, Carl E. Hoge, and Edward J. Derian, filed November 8, 2001.

**Please delete the paragraph at page 26 extending from line 16 through line 19, and insert therefor the following replacement paragraph:**

Application Serial No. [[--/---,---,]]10/022,454, entitled "ULTRA LOW IMPEDANCE POWER INTERCONNECTION SYSTEM FOR ELECTRONIC PACKAGING," by Joseph T. DiBene II, David H. Hartke, Carl E. Hoge, and Edward J. Derian, filed October 30, 2001, and now issued as U.S. Patent No. 6,556,455, which is a continuation in part of the following U.S. Patent Application: